



ASMJP.137AUS

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Yasuyoshi Hyodo, et al. )  
App. No. : 10/644,195 )  
Filed : August 20, 2003 )  
For : METHOD OF FORMING SILICON- )  
CONTAINING INSULATION FILM )  
HAVING OLOW DIELECTRIC )  
CONSTANT AND LOW FILM )  
STRESS )  
Examiner : Unknown )

ESTABLISHMENT OF RIGHT OF ASSIGNEE TO TAKE ACTION  
AND  
REVOCATION AND POWER OF ATTORNEY

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The undersigned is empowered to act on behalf of the assignee below (the "Assignee"). A true copy of the original Assignment of the above-captioned application from the inventor(s) to the Assignee is attached hereto. This Assignment represents the entire chain of title of this invention from the Inventor(s) to the Assignee.

I declare that all statements made herein are true, and that all statements made upon information and belief are believed to be true, and further, that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001, and that willful, false statements may jeopardize the validity of the application, or any patent issuing thereon.

The undersigned hereby revokes any previous powers of attorney in the subject application, and hereby appoints the registrants of Knobbe, Martens, Olson & Bear, LLP, 2040

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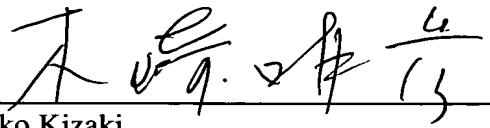
Main Street, Fourteenth Floor, Irvine, California 92614, Telephone (949) 760-0404, **Customer No. 20,995**, as its attorneys with full power of substitution and

revocation to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected herewith. This appointment is to be to the exclusion of the inventor(s) and his attorney(s) in accordance with the provisions of 37 C.F.R. § 3.71.

Please use **Customer No. 20,995** for all communications.

ASM JAPAN K.K.

Dated: October 2, 2003

By:   
Akihiko Kizaki

Title: Paten Manager

Address: 23-1, 6-chome, Nagayama  
Tama-shi, Tokyo 206-0025 Japan

ASSIGNMENT

WHEREAS, We, Yasuyoshi Hyodo, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Nobuo Matsuki, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Masashi Yamaguchi, Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Atsuki Fukazawa, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, Naoki Ohara, Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, and Yijun Liu, Japanese citizen, residing at 3440 East University Drive, Phoenix, AZ, 85034 USA, have invented certain new and useful improvements in a METHOD OF FORMING SILICON-CONTAINING INSULATION FILM HAVING LOW DIELECTRIC CONSTANT AND LOW FILM STRESS for which we have executed an application for Letters Patent in the United States, on August 20, 2003 as Application Serial No. 10/644,195;

AND WHEREAS, ASM JAPAN K. K.(hereinafter "ASSIGNEE"), a Japan Corporation, with its principal place of business at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 25 day of September, 2003

兵頭 靖得  
Yasuyoshi Hyodo

This 25 day of September, 2003

Matsumoto  
Nobuo Matsuki

This 25 day of September, 2003

山口 正史  
Masashi Yamaguchi

This 25 day of September, 2003

深澤 篤毅  
Atsuki Fukazawa

Witness

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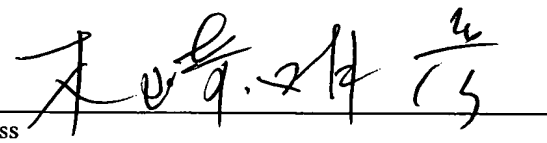
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This 25 day of 9, 2003

  
Naoki Ohara

This 25 day of September, 2003

  
Yijun Liu

  
Witness

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